OV5645 5-megapixel product brief





High Quality 5-Megapixel Photography and HD Video for Low-Cost Mobile Devices

available in a lead-free package OmniVision's OV5645 is a high performance, 5-megapixel system-on-chip (SOC) ideally suited for the cost-sensitive segment of the mobile handset market. The CameraChip™ sensor's single MIPI port replaces both a bandwidth-limited DVP interface and a costly embedded JPEG compressor, allowing the new OV5645 sensor to save significant silicon area and cost. An embedded autofocus control with voice coil motor driver offers further cost savings for the end user, making the OV5645 a highly attractive alternative to other 5-megapixel sensors currently on the market.

The OV5645 also features a new picture-in-picture (PIP) architecture that offers an easy-to-implement, low-cost dual camera system solution for mobile handsets and smartphones. The feature is based on a master/slave configuration where a front-facing camera (OV7965) can be connected through the OV5645 master camera, enabling a two-camera system with PIP functionality without the need for an additional MIPI interface into the baseband processor.

Built on OmniVision's 1.4-micron OmniBSI[™] pixel architecture, the OV5645 offers high performance 5-megapixel photography and 720p HD video at 60 frames per second (FPS) and 1080p HD video at 30 FPS with complete user control over formatting and output data transfer. The sensor's 720p HD video is captured in full field-of-view with 2 x 2 binning, which doubles the sensitivity and improves the signal-to-noise ratio (SNR). A unique post-binning, re-sampling filter function removes zigzag artifacts around slant edges and minimizes spatial artifacts to deliver even sharper, crisper color images.

Find out more at www.ovt.com.



Applications

- Cellular Phones
- Toys

- PC Multimedia
- Digital Still Cameras

Product Features

- 1.4 µm x 1.4 µm pixel with OmniBSI+™ technology for high performance (high sensitivity, low crosstalk, low noise, improved quantum efficiency)
- optical size of 1/4"
- automatic image control functions: automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), automatic 50/60 Hz luminance detection, and automatic blacklevel calibration (ABLC)
 dual lane MIPI output interface
- image quality controls: color saturation, embedded 1.5V regulator for core hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling
- support for output formats: RAW RGB, RGB565/555/444, YUV422/420, YCbCr422
- support for video or snapshot operations
- support for internal and external frame synchronization for frame exposure mode
- support for LED and flash strobe mode

Functional Block Diagram

- support for horizontal and vertical sub-sampling, binning
- support for minimizing artifacts on binned image
- support for data compression output
- support for anti-shake
- standard serial SCCB interface
- power
- programmable I/O drive capability, I/O tri-state configurability
- support for black sun cancellation
- support for images sizes: 5 megapixel, and any arbitrary size scaling down from 5 megapixel
- support for auto focus control (AFC) with embedded AF VCM driver
- embedded microcontroller
- suitable for module size of 8.5 x 8.5 x <6mm with both CSP and RW packaging

- OV05645-A66A (color, lead-free, 66-pin CSP3)
- OV05645-G04A (color, chip probing, 200 µm backgrinding, reconstructed wafer)

Product Specifications

- active array size: 2592 x 1944
- power supply: core: 1.5V ±5% (with embedded 1.5 regulator) - analog: 2.6 - 3.0V (2.8V typical) - I/O: 1.8V / 2.8V
- temperature range:
 operating: -30°C to 70°C junction
- temperature stable image: 0°C to 50°C junction temperature
- output formats: 8-/10-bit RGB RAW, RGB565/555/444, YUV422/420, YCbCr422 output
- lens size: 1/4"
- lens chief ray angle: 29.1°

- input clock frequency: 6 27 MHz
- max S/N ratio: 36 dB
- maximum image transfer rate:
 QSXGA (2592X1944): 15 fps - 1080p: 30 fps - 1280x960: 45 fps
 - 720p: 60 fps
- shutter: rolling shutter / frame exposure
- maximum exposure interval: 1964 × t_{ROW}
- **pixel size:** 1.4 μm x 1.4 μm
- image area: 3673.6 µm x 2738.4 µm
- package/die dimensions:
 CSP3: 6200 μm x 4860 μm
 COB: 6190 μm x 4850 μm



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USA

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